



2007 International Symposium on Semiconductor Manufacturing

Conference Proceedings

October 15 – 17, 2007
Santa Clara Marriott
Santa Clara, California

ISSM 2007
Marriott Hotel ~Santa Clara, CA U.S.A.
October 15-17, 2007

Monday, October 15, 2007

General Conference Activities

| | | |
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| 7:00 AM | Registration Desk Open for Check-in | California Ballroom Registration Desk |
| 7:00 AM | Speaker Ready Room available for speaker review and preparation | |
| 7:00 AM | Speaker Breakfast (for speakers/ co-chairs scheduled on Monday) | Hall of Cities- Seattle |
| 12:00 PM | Attendee Lunch | Hall of Cities |
| 6:15 PM | Attendee Dinner Reception | Pool and Courtyard |

Keynote Speeches and Addresses

California Ballroom, Salon 6

| | | |
|---------|---|----|
| 8:00 AM | Tom Sonderman, International Program Committee Chairman <i>Welcome Note</i> | |
| 8:10 AM | Rich Karlgaard, Publisher of Forbes <i>Twelve Types of Innovation That Will Save Your Company</i> | |
| 9:05 AM | Susuma Kohyama, President and CEO, Covalent Materials Corp. <i>Rising Role of Indirect Materials for Semiconductor Manufacturing</i> | 75 |
| 1:00 PM | Paul Westbrook, Senior Technologist, Texas Instruments <i>Less is More</i> | 79 |

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California Ballroom, Salon 6

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| 10:35 AM | MS-O-139 | Evolutionary Business Models and Inter-Firm Engineering Processes Between the Foundry and Fabless in the Semiconductor Industry | 275 |
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Tuesday, October 16, 2007

General Conference Activities

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| 7:00 AM | Registration Desk Open for Check-in | California Ballroom Registration Desk |
| 7:00 AM | Speaker Ready Room available for speaker review and preparation | |
| 7:00 AM | Speaker Breakfast (for speakers/ co-chairs scheduled on Tuesday) | Hall of Cities- Seattle |
| 12:05 PM | Attendee Lunch | Hall of Cities |
| 5:15 PM | Interactive Poster Session Reception | Grand Ballroom |

Keynote Speeches and Addresses California Ballroom, Salon 6

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|----------|--|
| 8:00 AM | Tom Sonderman, International Program Committee Chairman <i>Welcome Note</i> |
| 8:15 AM | Mark Durcan, COO, Micron <i>Optimizing Memory Operations at the Leading Edge</i> |
| 9:10 AM | Jackson Hu, CEO, UMC <i>Challenges and Opportunities Facing the Semiconductor Industry</i> 27 |
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| Tuesday, Track 1 Oral Presentations | California Ballroom, Salon 6 |
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California Ballroom, Salon 4

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| 7:00 AM | Speaker Ready Room available for speaker review and preparation |
| 7:00 AM | Speaker Breakfast (for speakers/ co-chairs scheduled on Wednesday) Hall of Cities- Seattle |
| 7:00 AM | Attendee Breakfast Hall of Cities |

Keynote Speeches and Addresses

California Ballroom, Salon 6

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| 8:00 AM | Tom Sonderman, International Program Committee Chairman <i>Welcome Note</i> |
| 8:10 AM | Michael Splinter, CEO, Applied Materials <i>Optimizing Fab Performance</i> |
| 9:05 AM | Susan Graham Johnston, Vice President, Volume System Operations, Sun Microsystems <i>"One Touch" Supply Chain.....</i> 53 |
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